

01576 U.S. PTO
07/21/03

The filing fee is calculated as follows:

	CLAIMS AS	FILED	SMALL ENTITY		OTHER THAN A SMALL ENTITY
FOR	NO. FILED	NO. EXTRA	RATE FEE		RATE FEE
BASIC FEE			\$370		\$750
Total Claims	3 -20=	-0-	X9=	or	X18= -0-
Indep claims	2 -3=	-0-	X42=	or	X84= -0-
[] Multiple	Dep claims		+140=	or	+280= -0-
			TOTAL		TOTAL \$750

X A check in the amount of \$750.00 is enclosed.

 The Commissioner is hereby authorized to charge \$ to the credit card identified in the attached Credit Card Payment Form.

X The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 20-1424. A duplicate copy of this sheet is attached.

 x Any additional fees under 37 CFR 1.16 for the presentation of extra claims.

 x Any patent application processing fees under 37 CFR 1.17.

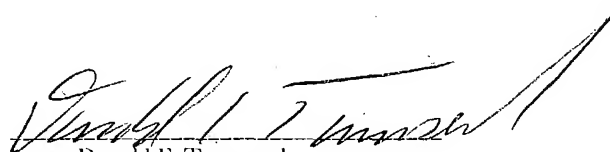
X The Commissioner is hereby authorized to charge payment of the following fees during the pendency of this application or credit any overpayment to Deposit Account No. 20-1424. A duplicate copy of this sheet is attached.

 x Any patent application processing fees under 37 CFR 1.17, including extension of time fees.

 x Any filing fees under 37 CFR 1.16 for the presentation of extra claims.

Date: July 21, 2003

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Donald E. Townsend
Reg. No. 22,069

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

CONTINUATION-IN-PART PATENT APPLICATION TRANSMITTAL LETTER

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Transmitted herewith for filing pursuant to 37 C.F.R. § 1.53(b) is the Continuation-In-Part patent application of:

INVENTOR(S):

Shigeyuki OGAWA
c/o Shiseido Research Center 1, Shiseido Co., Ltd.
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1050, Nippa-cho, Kohoku-ku
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Japan

**FOR: ANTISEPTIC /ANTIFUNGAL AGENT AND ENDERMIC LINIMENT COMPOSITION WHICH
CONTAINS IT**

Enclosed are:

- X Specification, Claims and Abstract
- An Assignment of the invention to: Shiseido Company, Ltd.
- A certified copy of the Japanese priority application No. * filed *.
- An associate power of attorney.
- A verified statement to establish small entity status under 37 CFR § 1.9 and 1.27.
- A Preliminary Amendment.
- X A Notice of Informal Filing of New Patent Application.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
S. OGAWA, et al.

Serial No.: To Be Assigned

Art Unit: To Be Assigned

Filed: Concurrently Herewith

Examiner: To Be Assigned

For: Antiseptic/Antifungal Agent And Endermic Liniment Composition
Which Contains It

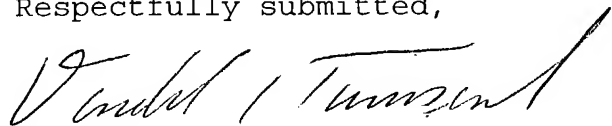
INFORMAL FILING OF NEW PATENT APPLICATION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450
BOX PATENT APPLICATIONS

Sir:

The undersigned has been authorized by the Applicants,
Shigeyuki OGAWA and Yoshio ASAKA, to file the enclosed patent
application, and to defer filing of the Declaration/Power of
Attorney.

Respectfully submitted,



Donald E. Townsend
Reg. No. 22,069

Date: July 21, 2003

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